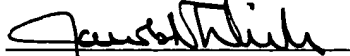


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Jacob N. Erlich
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Drew Guckenberger, et al.

Examiner: N/A

Application Serial Number: N/A

Group Art Unit: N/A

Filed: Herewith

For: LOW-VOLTAGE, LOW-POWER TRANSIMPEDANCE AMPLIFIER
ARCHITECTURE

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

This Information Disclosure Statement (Form PTO-1449) (including copies of non-U.S. patent references) is submitted under 37 CFR 1.97(b).

REMARKS

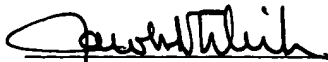
Applicant submits herewith an Information Disclosure Statement under 37 CFR 1.97(b).

The following information is presented in the event that a call may be deemed desirable by the Examiner:

JACOB N. ERLICH (617) 854-4000.

Respectfully submitted,
Drew Guckenberger, et al., Applicants

Dated: March 31, 2004

By: 
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U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

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APPLICANT: Drew Guckenberger, et al.

EXAMINER: N/A

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CONFIRMATION NO.: N/A

U.S. PATENT DOCUMENTS

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EXAMINER**DATE CONSIDERED**